# DUSEU

**NL27WZ02** 

Features

operating from a 1.65 V to 5.5 V supply.

• 2.5 ns  $t_{PD}$  at  $V_{CC} = 5 V (typ)$ 

• Source/Sink 24 mA at 3.0 V

• Chip Complexity < 100 FETs

Α1

B1 A2

B2

≥1

≥1

**PPAP** Capable

Compliant

#### **Dual 2-Input NOR Gate** MARKING DIAGRAMS 8888 XXXX The NL27WZ02 is a high performance dual 2-input NOR Gate US8 ALYW **US SUFFIX CASE 493** ᆸᆸᆸᇉ Commercial • Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation UDFN8, 1.95x1.0 **MU1 SUFFIX** ХМ • Inputs/Outputs Overvoltage Tolerant up to 5.5 V CASE 517CA • IOFF Supports Partial Power Down Protection UDFN8, 1.6x1.0 • Available in US8, UDFN8 and UQFN8 Packages ΧM **MU2 SUFFIX** CASE 517BY 1 • -Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and UDFN8, 1.45x1.0 **MU3 SUFFIX** ΧМ • These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS CASE 517BZ UQFN8, 1.6x1.6 MQ1 SUFFIX XX M= CASE 523AN Y1 Y2 UQFN8, 1.4x1.2 XM MQ2 SUFFIX 10 CASE 523AS Figure 1. Logic Symbol X, XX, XXXX = Specific Device Code = Assembly Location А L = Lot Code Y = Year Code W = Week Code

Μ

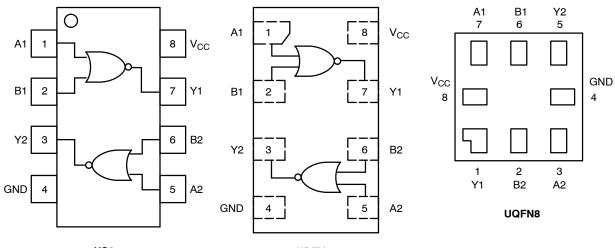
### **ORDERING INFORMATION**

= Date Code = Pb-Free Package

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

August, 2023 - Rev. 17

## NL27WZ02



US8

UDFN8

Figure 2. Pinout

#### **PIN ASSIGNMENT** (US8 / UDFN8)

Pin	Function
1	A1
2	B1
3	Y2
4	GND
5	A2
6	B2
7	Y1
8	V <sub>CC</sub>

#### **PIN ASSIGNMENT** (UQFN8)

	· · ·
Pin	Function
1	Y1
2	B2
3	A2
4	GND
5	Y2
6	B1
7	A1
8	V <sub>CC</sub>

## FUNCTION TABLE

Inp	Output	
Α	В	Y
L	L	Н
L	Н	L
Н	L	L
Н	Н	L

H = HIGH Logic Level L = LOW Logic Level

## MAXIMUM RATINGS

Symbol	Characteristics		Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +6.5	V
V <sub>IN</sub>	DC Input Voltage		–0.5 to +6.5	V
		-Mode (High or Low State) Tri-State Mode (Note 1) er-Down Mode (V <sub>CC</sub> = 0 V)	-0.5 to V <sub>CC</sub> + 0.5 -0.5 to +6.5 -0.5 to +6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < GND	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < GND	-50	mA
IOUT	DC Output Source/Sink Current	±50	mA	
I <sub>CC</sub> or I <sub>GND</sub>	DC Supply Current per Supply Pin or Ground Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 secs		260	°C
ТJ	Junction Temperature Under Bias		+150	°C
$\theta_{JA}$	Thermal Resistance (Note 2)	US8 UQFN8 UDFN8	250 210 231	°C/W
PD	Power Dissipation in Still Air	ower Dissipation in Still Air US8 UQFN8 UDFN8		mW
MSL	Moisture Sensitivity		Level 1	-
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	-
$V_{\text{ESD}}$	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model	2000 1000	V
I <sub>Latchup</sub>	Latchup Performance (Note 4)		±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Applicable to devices with outputs that may be tri-stated.

 Measured with minimum pad spacing on an FR4 board, using 10mm-by-1inch, 2 ounce copper trace no air flow per JESD51-7.
 HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A. 4. Tested to EIA/JESD78 Class II.

## **RECOMMENDED OPERATING CONDITIONS**

Symbol	Chara	Min	Max	Unit	
V <sub>CC</sub>	Positive DC Supply Voltage		1.65	5.5	V
V <sub>IN</sub>	DC Input Voltage		0	5.5	V
V <sub>OUT</sub>	DC Output Voltage	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode (V <sub>CC</sub> = 0 V)	0 0 0	V <sub>CC</sub> 5.5 5.5	
T <sub>A</sub>	Operating Temperature Range		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time	$\begin{array}{l} V_{CC} = 1.65 \ V \ \text{to} \ 1.95 \ \text{V} \\ V_{CC} = 2.3 \ \text{V} \ \text{to} \ 2.7 \ \text{V} \\ V_{CC} = 3.0 \ \text{V} \ \text{to} \ 3.6 \ \text{V} \\ V_{CC} = 4.5 \ \text{V} \ \text{to} \ 5.5 \ \text{V} \end{array}$	0 0 0 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

			V <sub>CC</sub>	T <sub>A</sub> = 25°C		C	–55°C ≤ T	A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Мах	Units
VIH	High-Level Input		1.65 to 1.95	$0.65 \times V_{CC}$			$0.65 \times V_{CC}$		V
	Voltage		2.3 to 5.5	$0.70 \times V_{CC}$			$0.70 \times V_{CC}$		
VIL	Low-Level Input		1.65 to 1.95			0.35 x V <sub>CC</sub>		0.35 x V <sub>CC</sub>	V
	Voltage		2.3 to 5.5			0.30 x V <sub>CC</sub>		0.30 x V <sub>CC</sub>	
V <sub>OH</sub>	High-Level Output Voltage	$ \begin{array}{l} V_{IN} = V_{IH} \text{ or } V_{IL} \\ I_{OH} = -100 \ \mu A \\ I_{OH} = -4 \ m A \\ I_{OH} = -8 \ m A \\ I_{OH} = -12 \ m A \\ I_{OH} = -16 \ m A \\ I_{OH} = -24 \ m A \\ I_{OH} = -32 \ m A \end{array} $	1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5	V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8	V <sub>CC</sub> 1.4 2.1 2.4 2.7 2.5 4.0		V <sub>CC</sub> - 0.1 1.29 1.9 2.2 2.4 2.3 3.8		V
V <sub>OL</sub>	Low-Level Output Voltage		1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5		- 0.08 0.2 0.22 0.28 0.38 0.38	0.1 0.24 0.3 0.4 0.4 0.55 0.55	- - - - -	0.1 0.24 0.3 0.4 0.4 0.55 0.55	>
I <sub>IN</sub>	Input Leakage Current	$V_{IN}$ = 5.5 V or GND	1.65 to 5.5	-	-	±0.1	-	±1.0	μA
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0	-	-	1.0	-	10	μA
I <sub>CC</sub>	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5	-	-	1.0	-	10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

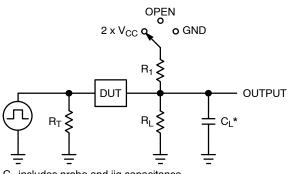
## AC ELECTRICAL CHARACTERISTICS

				٦	「 <sub>A</sub> = 25°C	)	T <sub>A</sub> = -55	to 125°C	
Symbol	Parameter	V <sub>CC</sub> (V)	Test Conditions	Min	Тур	Max	Min	Max	Units
t <sub>PLH</sub> , Propagation Delay, t <sub>PHL</sub> (A or B) to Y		1.65 to 1.95	$\begin{array}{l} C_L = 15 \ \text{pF} \\ R_L = 1 \ \text{M}\Omega \\ R_1 = \text{Open} \end{array}$	-	7.4	9.5	-	9.7	ns
	(A or B) to Y	2.3 to 2.7		-	3.3	5.4	-	5.8	
		3.0 to 3.6		-	2.6	3.9	-	4.3	
		4.5 to 5.5		-	1.9	3.1	-	3.3	
	3.0 to 3.6	$C_{L} = 50 \text{ pF},$	-	3.2	4.8	-	5.2		
		4.5 to 5.5	$R_L^-$ = 500 $\Omega$ , $R_1$ = Open	-	2.5	3.7	_	4.0	

### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 5.5 V, $V_{IN}$ = 0 V or $V_{CC}$	2.5	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC}$ = 5.5 V, $V_{IN}$ = 0 V or $V_{CC}$	2.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub> 10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub>	9 11	pF

5.  $C_{PD}$  is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation:  $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$ .  $C_{PD}$  is used to determine the no-load dynamic power consumption;  $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$ .

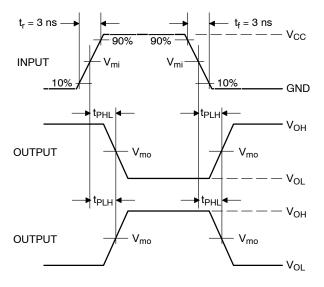


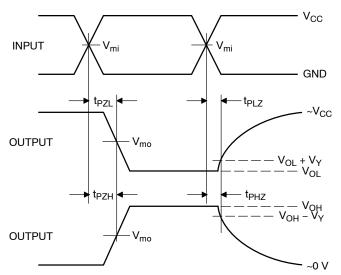
Switch Position	C <sub>L</sub> , pF	$R_{L}, \Omega$	R <sub>1</sub> , Ω	
Open	See AC Characteristics Table			
$2 \times V_{CC}$	50	500	500	
GND	50 500		500	
	Position Open 2 x V <sub>CC</sub>	Position         See AC Character           Open         See AC Character           2 x V <sub>CC</sub> 50	Position         Epril           Open         See AC Characteristics Tat           2 x V <sub>CC</sub> 50	

X = Don't Care

 $C_L$  includes probe and jig capacitance  $R_T$  is  $Z_{OUT}$  of pulse generator (typically 50  $\Omega)$  f = 1 MHz

## Figure 3. Test Circuit





## Figure 4. Switching Waveforms

		Vm		
V <sub>CC</sub> , V	V <sub>mi</sub> , V	t <sub>PLH</sub> , t <sub>PHL</sub>	t <sub>PZL</sub> , t <sub>PLZ</sub> , t <sub>PZH</sub> , t <sub>PHZ</sub>	V <sub>Y</sub> , V
1.65 to 1.95	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.15
2.3 to 2.7	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.15
3.0 to 3.6	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.3
4.5 to 5.5	V <sub>CC</sub> /2	V <sub>CC</sub> /2	V <sub>CC</sub> /2	0.3

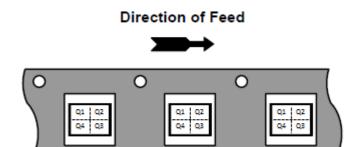
### **DEVICE ORDERING INFORMATION**

Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping <sup>†</sup>
NL27WZ02USG	US8	L3	Q4	3000 / Tape & Reel
NL27WZ02MQ1TCG (Please contact <b>onsemi</b> )	UQFN8, 1.6 x 1.6, 0.5P	TBD	TBD	3000 / Tape & Reel
NL27WZ02MU1TCG	UDFN8, 1.95 x 1.0, 0.5P	AL	Q4	3000 / Tape & Reel
NL27WZ02MU1TWG	UDFN8, 1.95 x 1.0, 0.5P	AM	Q1	3000 / Tape & Reel
NL27WZ02MU3TCG	UDFN8, 1.45 x 1.0, 0.35P	J	Q4	3000 / Tape & Reel
NL27WZ02MU2TCG	UDFN8, 1.6 x 1.0, 0.4P	AH	Q4	3000 / Tape & Reel
NL27WZ02MQ2TCG (Please contact <b>onsemi</b> )	UQFN8, 1.4 x 1.2, 0.4P	TBD	TBD	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

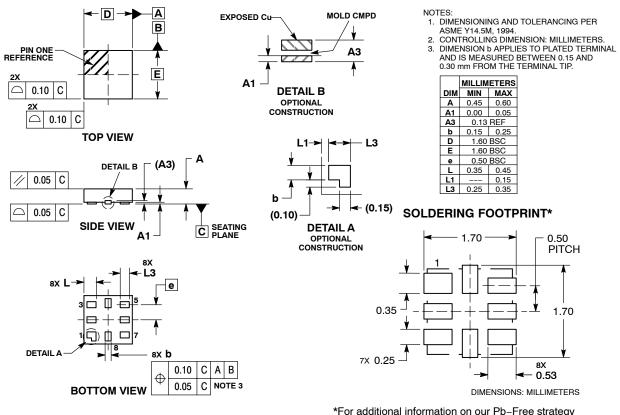
\*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

## Pin 1 Orientation in Tape and Reel



### PACKAGE DIMENSIONS

UQFN8, 1.6x1.6, 0.5P CASE 523AN ISSUE O

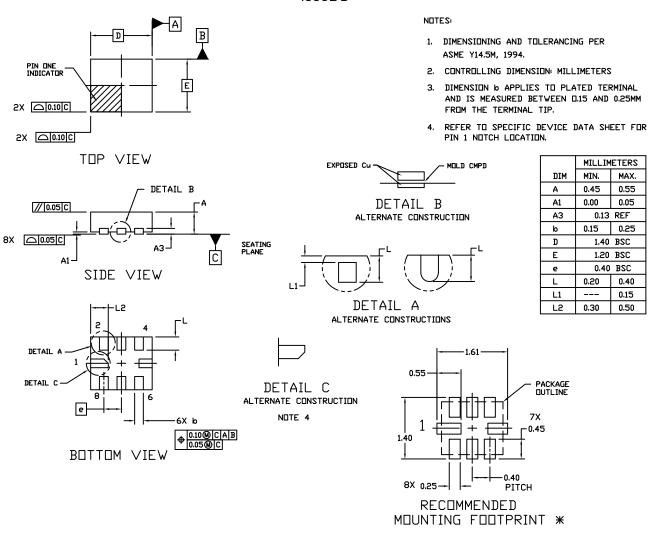


\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## NL27WZ02

### PACKAGE DIMENSIONS

UQFN8, 1.4x1.2, 0.4P CASE 523AS ISSUE B



\* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# semi



SEATING PLANE

8X 0.68

n 甶

0.50

RECOMMENDED

MOUNTING FOOTPRINT

PITCH

8X 0.30-

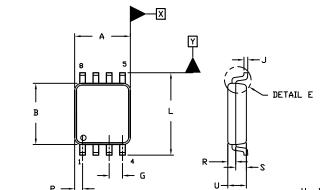
⊕0.10 (0.004) W T X Y

### US8 **CASE 493**

#### ISSUE F

DETAIL E

DATE 01 SEP 2021



-c

3.40

ж

0.10 (0.004) T

NOTES:

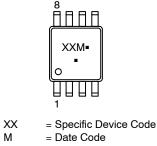
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS

R 0.10 TYP

- DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSION, З. OR GATE BURR. MOLD FLASH, PROTRUSION, OR GATE BURR SHALL NOT EXCEED 0.14 (0.0055') PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH AND PROTRUSION SHALL NOT 4. EXCEED 0.14 (0.0055") PER SIDE.
- LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 5. 0.0076-0.0203 MM (0.003-0.008").
- ALL TELERANCE UNLESS ETHERWISE SPECIFIED ±0.0508 MM (0.002"). 6.

	MILLIMETERS		INC	HES
DIM	MIN.	MAX.	MIN.	MAX.
Α	1.90	2.10	0.075	0.083
В	2.20	2.40	0.087	0.094
С	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50	BSC	0.020	BSC
Н	0.40	REF	0.016 REF	
J	0.10	0.18	0.004	0.007
к	0.00	0.10	0.000	0.004
L	3.00	3.25	0.118	0.128
м	0*	6*	0*	6*
N	0*	10*	0*	10*
Р	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V	0.12	BSC	0.005	BSC

### GENERIC **MARKING DIAGRAM\***



= Pb-Free Package

(Note: Microdot may be in either location)

Μ

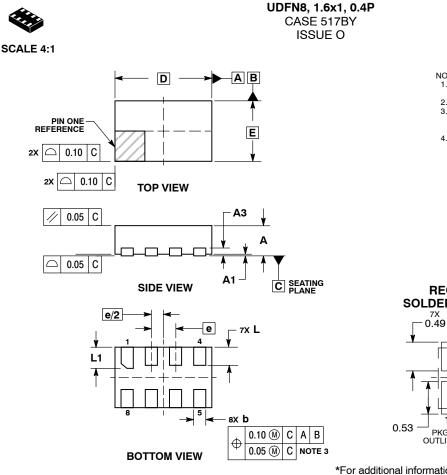
\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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#### DATE 18 MAY 2011

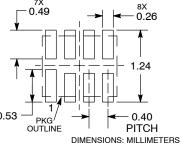
NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- CONTENTIOLING DIMENSION: MILLIMETERS.
   DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP. 4. PACKAGE DIMENSIONS EXCLUSIVE OF

	AND MOLD FLASH.						
	MILLIN	IETERS					
DIM	MIN	MAX	1				
Α	0.45	0.55					

Α	0.45	0.55		
A1	0.00	0.05		
A3	0.13 REF			
b	0.15	0.25		
D	1.60 BSC			
E	1.00 BSC			
е	0.40 BSC			
L	0.25	0.35		
11	0.30	0 40		

#### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.





1

X = Specific Device Code M = Date Code

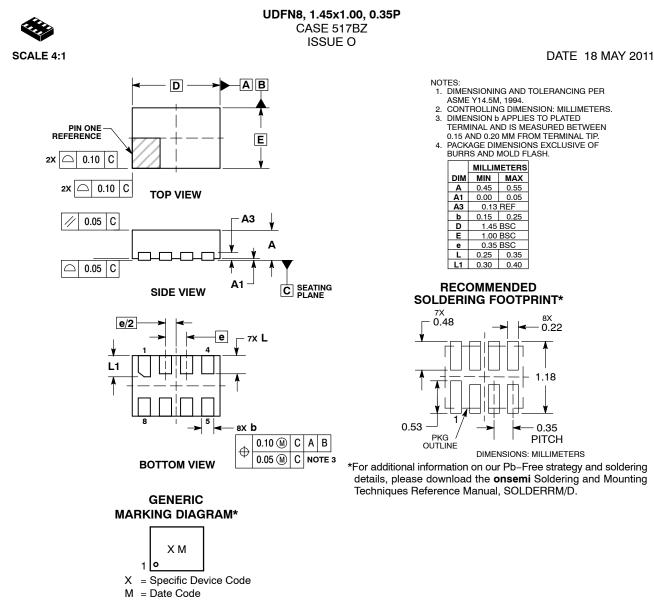
\*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

 
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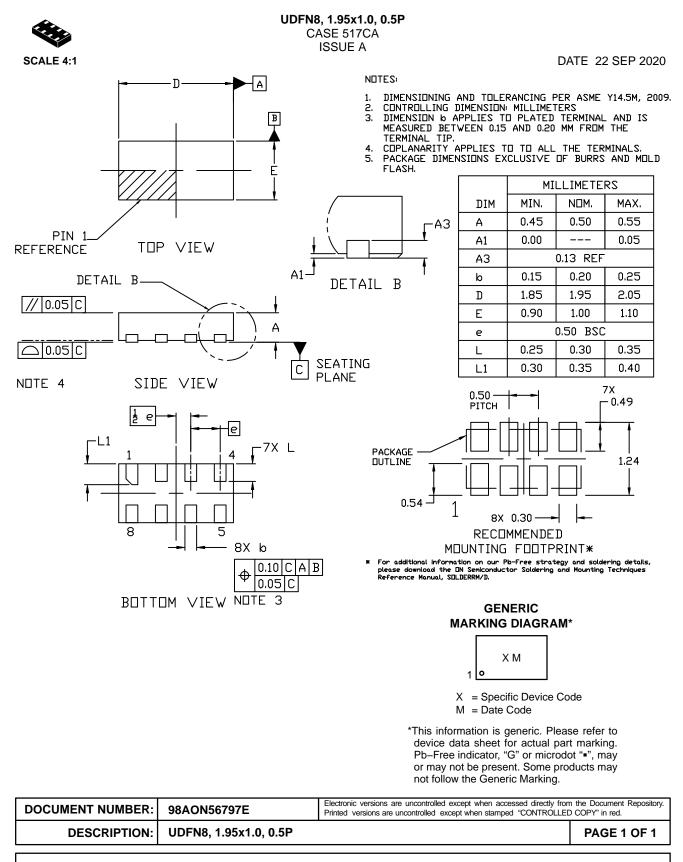
 
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